# 2SB0970 (2SB970)

## Silicon PNP epitaxial planar type

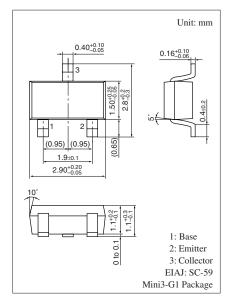
For low-voltage output amplification

#### Features

Storage temperature

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Symbol Rating Unit Collector-base voltage (Emitter open) V<sub>CBO</sub> -15V Collector-emitter voltage (Base open) V<sub>CEO</sub> -10V -7 V Emitter-base voltage (Collector open) $V_{EBO}$ Collector current $I_C$ -0.5А Peak collector current $I_{CP}$ -1Α Collector power dissipation $P_C$ 200 mW °C Junction temperature Ti 150



#### Marking Symbol: 1R

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

a						
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$	-15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -1  {\rm mA},  I_{\rm B} = 0$	-10			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = -10 \ \mu A, \ I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = -10 \text{ V}, I_E = 0$			-100	nA
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = -2 V, I_C = -0.5 A$	130		350	_
	h <sub>FE2</sub>	$V_{CE} = -2 V, I_C = -1 A$	60			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_{\rm C} = -0.4$ A, $I_{\rm B} = -8$ mA		- 0.16	- 0.30	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_{\rm C} = -0.4$ A, $I_{\rm B} = -8$ mA		- 0.8	-1.2	V
Transition frequency	f <sub>T</sub>	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		130		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		22		pF
(Common base, input open circuited)						

-55 to +150

T<sub>stg</sub>

°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

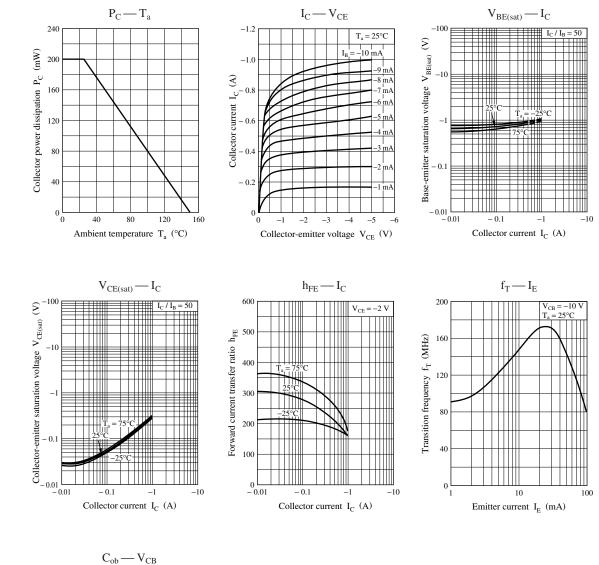
2. \*1: Pulse measurement

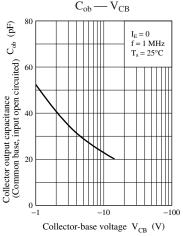
\*2: Rank classification

Rank	R	S
h <sub>FE1</sub>	130 to 220	180 to 350

Note) The part number in the parenthesis shows conventional part number.

## Panasonic





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